

BB02-CE :- 1.27mm (0.05") SOCKET, SINGLE ROW, STRAIGHT, THROUGH HOLE, 2 - 35 CONTACTS. PROFILE: 8.5MM

SPECIFICATIONS

CURRENT RATING 1 AMP
 INSULATOR RESISTANCE 1000 MEGOHMS MIN.
 CONTACT RESISTANCE 20m ohms MAX.
 DIELECTRIC WITHSTANDING AC 300 V
 OPERATING TEMPERATURE -40°C TO +105°C
 CONTACT MATERIAL PHOSPHOR BRONZE
 INSULATOR MATERIAL THERMOPLASTIC, UL 94V-0
 STANDARD: LCP + 30% G/F
 PLATING GOLD, TIN OR SELECTIVE OVER 30~50U" NICKEL
 SOLDERABILITY IR REFLOW: 280°C FOR 10 SEC
 WAVE: 250°C FOR 5-10 SEC
 MANUAL SOLDER: 380°C FOR 3-5 SEC

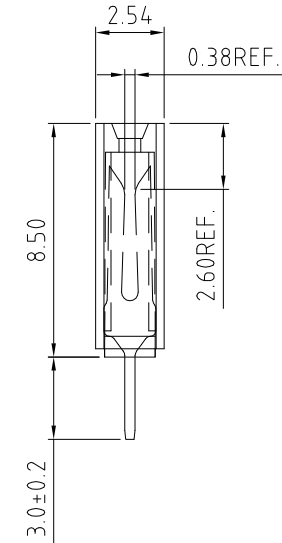
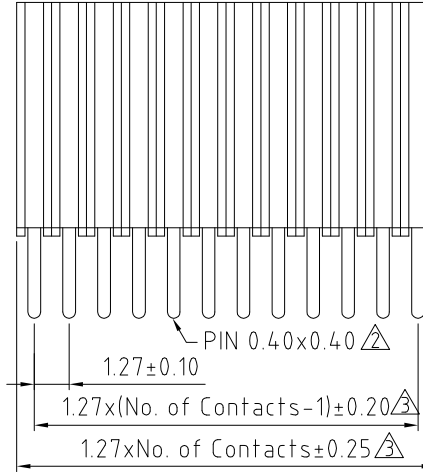
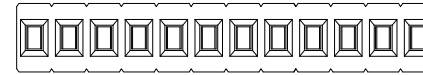
PACKED IN TUBE OR BOX.

NOTES:

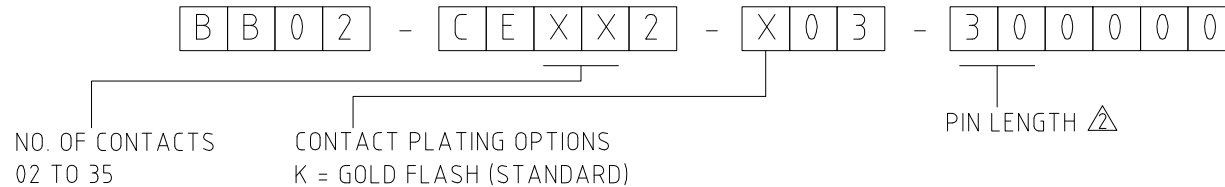
1. RECOMMENDED MATING PIN LENGTH : 4.0MM Δ

MATES WITH :- (0.46MM SQUARE PINS)

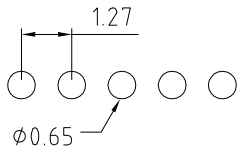
- Δ BB02-BL BB02-NH
- BB02-BM
- BB02-NM



HOW TO ORDER



- CONTACT PLATING OPTIONS
 K = GOLD FLASH (STANDARD)
 A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
 B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
 C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
 T = BRIGHT TIN
 M = MATT TIN
 D = GOLD FLASH ON CONTACT/BRIGHT TIN ON TAIL



RECOMMENDED PC BOARD HOLE LAYOUT Δ
 (TOLERANCE: ±0.05)

REV. DATE & DRN	10 06/07/02 - S1T RELEASE
11 17/02/05 - NYW	DRAWING MODIFICATION
12 27/07/05 - NYW	CHANGE NO. OF CONTACTS
13 29/07/05 - NYW	AMEND PCB LAYOUT
14 19/07/06 - NYW	AMEND PIN DIMENSION
15 05/06/07 - CHC	DIMENSION MODIFICATION
16 05/05/08 - CHC	DRAWING MODIFICATION
17 25/12/08 - CHC	AMEND MATES WITH
18 22/12/09 - NYW	ADD TOLERANCE
19 28/09/12 - NYW	AMEND MATING PART
20 06/07/15 - NYW	CHANGE INSULATOR TO LCP
	REMOVE PLATING OPTIONS E-G
	CHANGE MIN. PIN# FROM 3 TO 2

Scale: 5:1	THIRD ANGLE	Unstated Tolerances: X ± 0.30 X ± 0.25 XX ± 0.15 XXX ± 0.10	Material SEE NOTE
Drawn: CHC		Title SOCKET	NOT TO SCALE
App'd: XXXX		Date: 6 OCT. '15	Revision: 2.0
		UNIT: mm	

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Type: BB02-CE
BB02-CE
Drawing Number:
Sheet 1 of 1
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